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N-Channel 650V (D-S) Power MOSFET

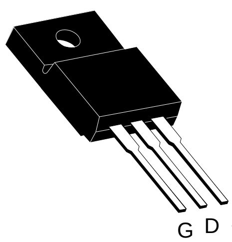
PRODUCT SUMMARY		
V_{DS} (V)	650	
$R_{DS(on)}$ (Ω)	V_{GS} = 10 V	2.5
Q_g (Max.) (nC)	48	
Q_{gs} (nC)	12	
Q_{gd} (nC)	19	
Configuration	Single	

FEATURES

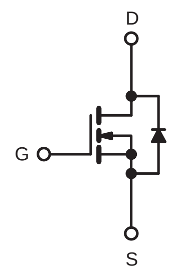
- Low Gate Charge Q_g Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Compliant to RoHS directive 2002/95/EC

Pb Available
RoHS*
COMPLIANT

TO-220 FULLPAK



Top View



N-Channel MOSFET

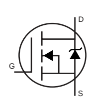
ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted					
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	650	V
Gate-Source Voltage			V_{GS}	± 30	
Continuous Drain Current[e]	V_{GS} at 10 V	T_C = 25 °C	I_D	4	A
Continuous Drain Current		T_C = 100 °C		3.8	
Pulsed Drain Current[a]			I_{DM}	18	
Linear Derating Factor				0.48	W/°C
Single Pulse Avalanche Energy[b]			E_{AS}	325	mJ
Repetitive Avalanche Current[a]			I_{AR}	4	A
Repetitive Avalanche Energy[a]			E_{AR}	6	mJ
Maximum Power Dissipation	T_C = 25 °C		P_D	30	W
Peak Diode Recovery dV/dt[c]			dV/dt	2.8	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)[d]	for 10 s			300	
Mounting Torque	6-32 or M3 screw			10	lbf · in
				1.1	N · m

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Starting T_J = 25 °C, L = 24 mH, R_G = 25 Ω, I_{AS} = 3.2 A (see fig. 12).
c. $I_{SD} \leq 3.2$ A, dI/dt ≤ 90 A/µs, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C.
d. 1.6 mm from case.
e. Drain current limited by maximum junction temperature.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	2.1	°C/W

SPECIFICATIONS T_J = 25 °C, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 μA	650	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA[d]	-	670	-	mV/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 30 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 650 V, V_{GS} = 0 V	-	-	25	μA
		V_{DS} = 520 V, V_{GS} = 0 V, T_J = 125 °C	-	-	250	μA
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 3.1 A[b]	-	2.5	-	Ω
Forward Transconductance	g_{fs}	V_{DS} = 50 V, I_D = 3.1 A	3.9	-	-	S
Dynamic						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz, see fig. 5	-	1080	-	pF
Output Capacitance	C_{oss}		-	177	-	pF
Reverse Transfer Capacitance	C_{rss}		-	7.0	-	pF
Output Capacitance	C_{oss}	V_{GS} = 0 V, V_{DS} = 1.0 V, f = 1.0 MHz	-	1912	-	pF
		V_{GS} = 0 V, V_{DS} = 520 V, f = 1.0 MHz	-	48	-	pF
Effective Output Capacitance	C_{oss} eff.	V_{GS} = 0 V, V_{DS} = 0 V to 520 V[c]	-	84	-	pF
Total Gate Charge	Q_g	V_{GS} = 10 V, I_D = 3.2 A, V_{DS} = 400 V see fig. 6 and 13[b]	-	-	48	nC
Gate-Source Charge	Q_{gs}		-	-	12	nC
Gate-Drain Charge	Q_{gd}		-	-	19	nC
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 325 V, I_D = 3.2 A, R_G = 9.1 Ω, R_D = 62 Ω, see fig. 10[b]	-	14	-	ns
Rise Time	t_r		-	20	-	ns
Turn-Off Delay Time	$t_{d(off)}$		-	34	-	ns
Fall Time	t_f		-	18	-	ns
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	4	A
Pulsed Diode Forward Current[a]	I_{SM}		-	-	21	A
Body Diode Voltage	V_{SD}	T_J = 25 °C, I_S = 3.2 A, V_{GS} = 0 V[b]	-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	T_J = 25 °C, I_F = 3.2 A, dI/dt = 100 A/μs[b]	-	493	739	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	2.1	3.2	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %.
c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}.
d. t = 60 s, f = 60 Hz.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

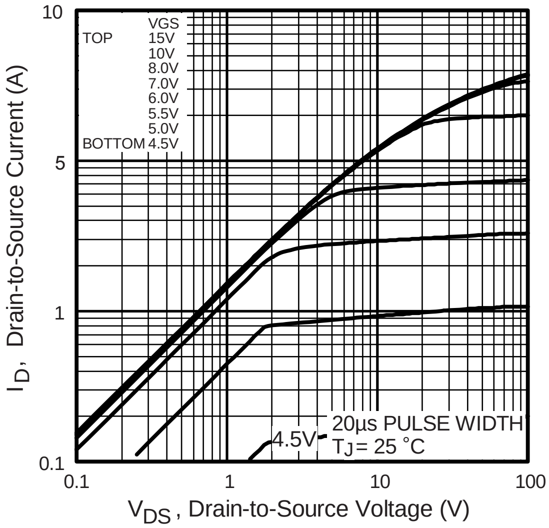


Fig. 1 - Typical Output Characteristics

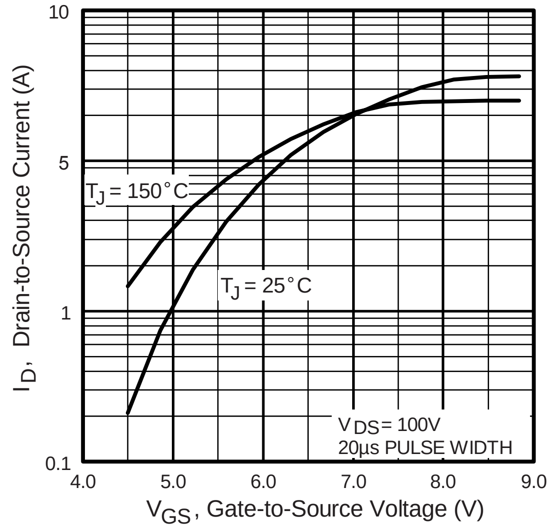


Fig. 3 - Typical Transfer Characteristics

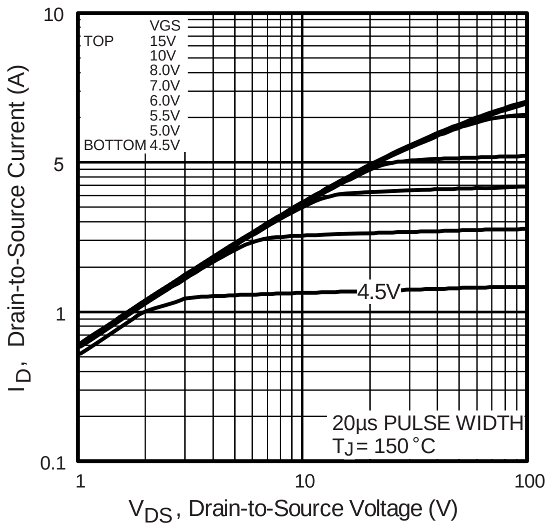


Fig. 2 - Typical Output Characteristics

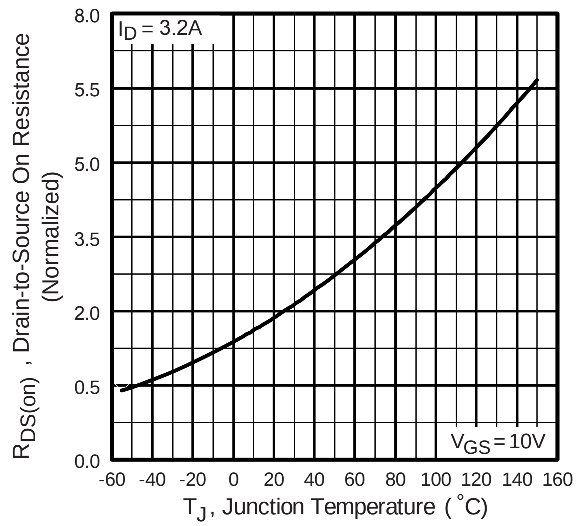


Fig. 4 - Normalized On-Resistance vs. Temperature

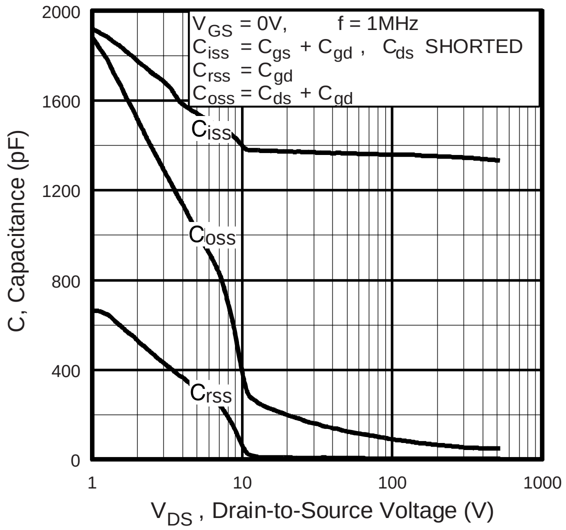


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

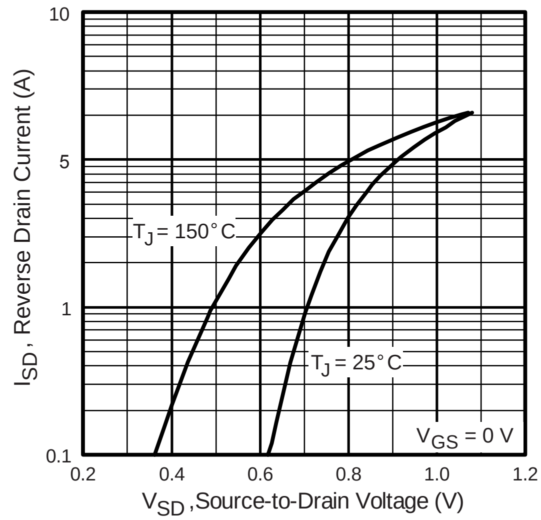


Fig. 7 - Typical Source-Drain Diode Forward Voltage

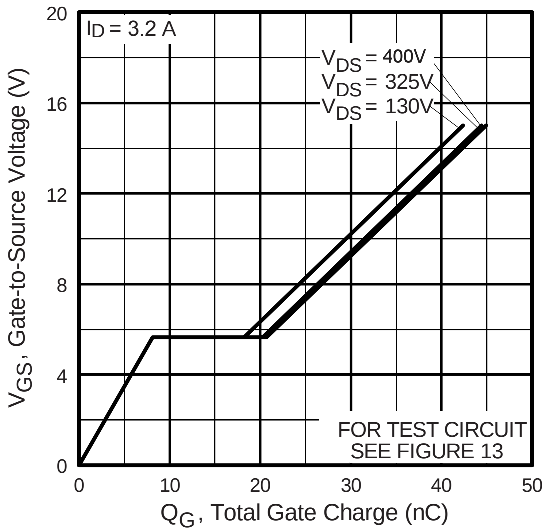


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

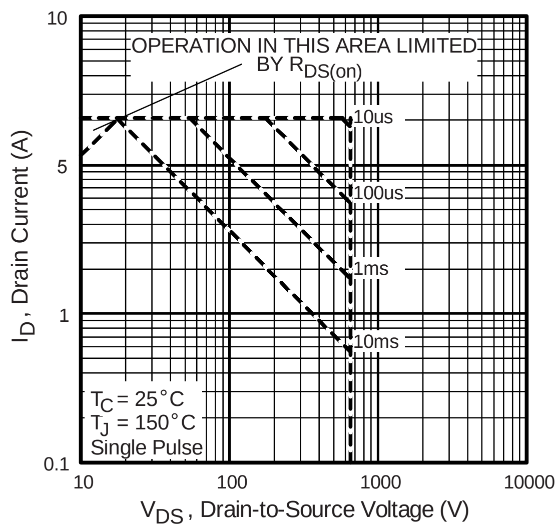


Fig. 8 - Maximum Safe Operating Area

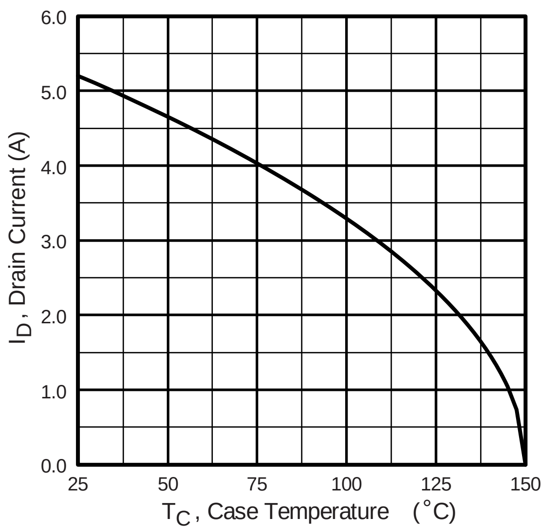


Fig. 9 - Maximum Drain Current vs. Case Temperature

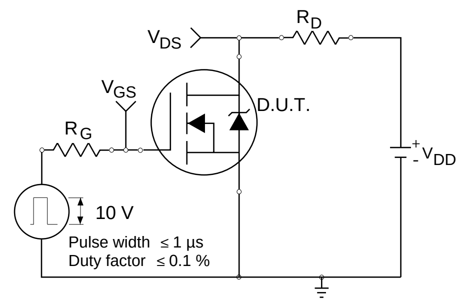


Fig. 10a - Switching Time Test Circuit

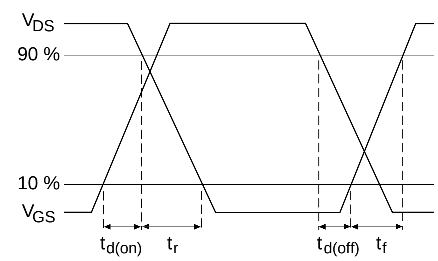


Fig. 10b - Switching Time Waveforms

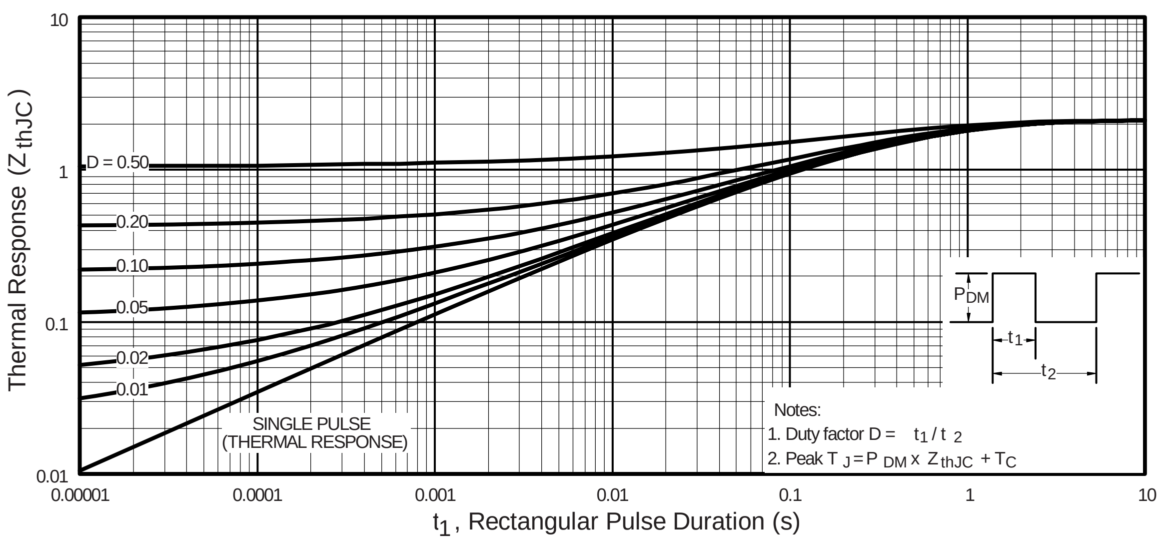


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

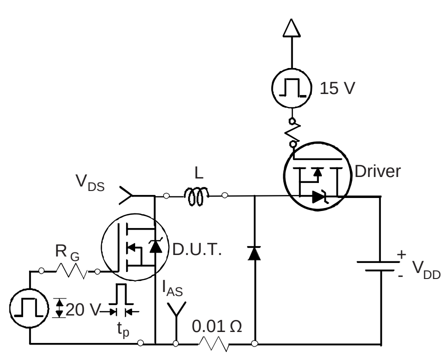


Fig. 12a - Unclamped Inductive Test Circuit

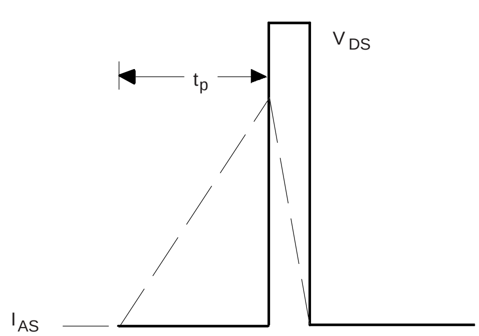


Fig. 12b - Unclamped Inductive Waveforms

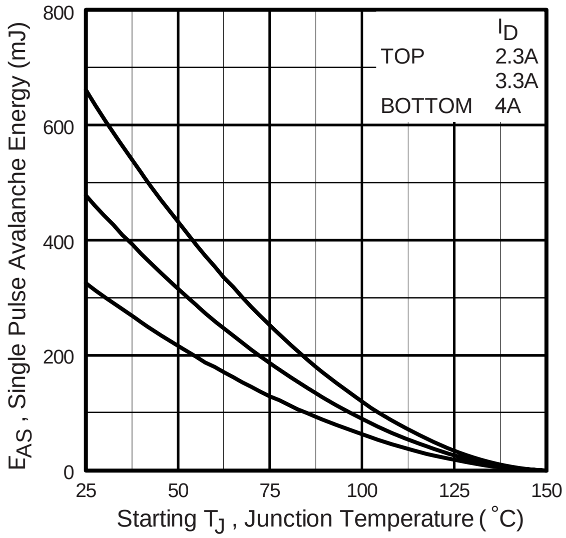


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

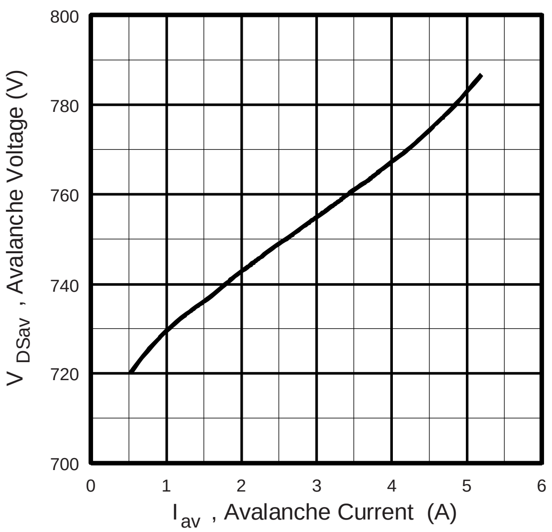


Fig. 12d - Typical Drain-to Source Voltage vs. Avalanche Current

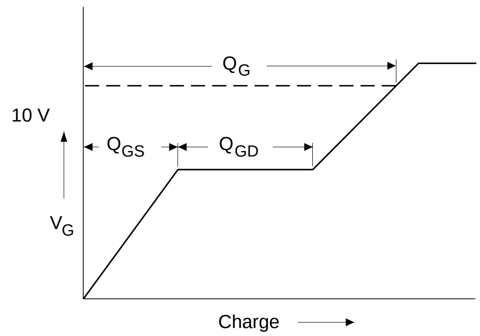


Fig. 13a - Basic Gate Charge Waveform

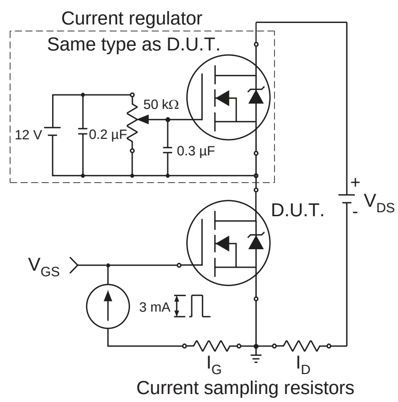
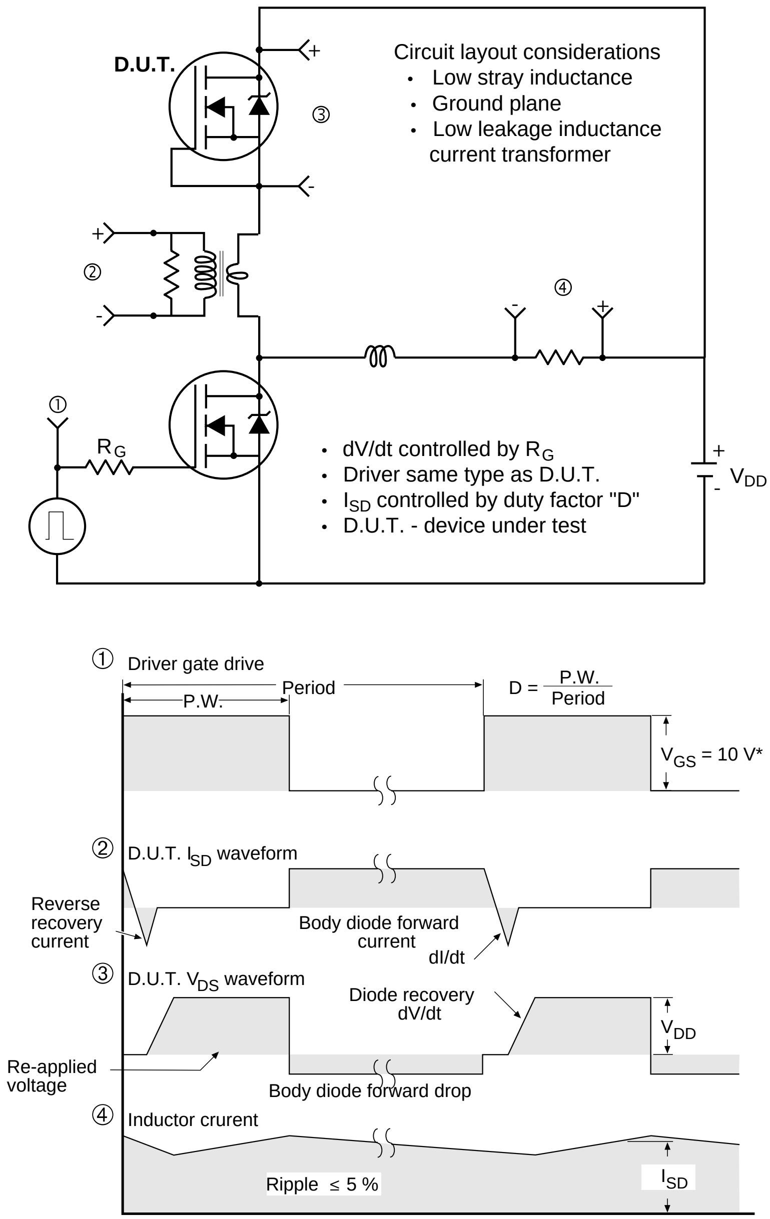


Fig. 13b - Gate Charge Test Circuit

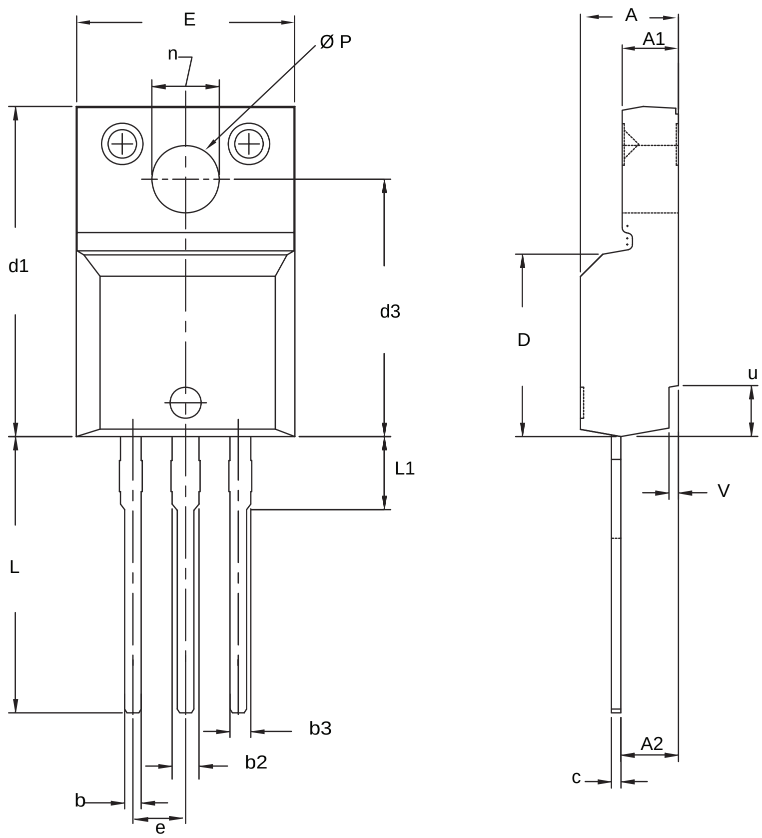
Peak Diode Recovery dV/dt Test Circuit



* V_{GS} = 5 V for logic level devices

Fig. 14 - For N-Channel

TO-220 FULLPAK (HIGH VOLTAGE)



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
c	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
e	2.54 BSC		0.100 BSC	
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
Ø P	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
v	0.400	0.500	0.016	0.020
ECN: X09-0126-Rev. B, 26-Oct-09 DWG: 5972				

Notes

1. To be used only for process drawing.
2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
3. All critical dimensions should C meet C_{pk} > 1.33.
4. All dimensions include burrs and plating thickness.
5. No chipping or package damage.

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